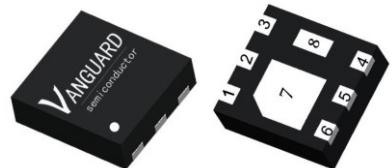


## Features

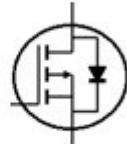
- P-Channel, -5V Logic Level Control
- Enhancement mode
- Low on-resistance  $R_{DS(on)}$  @  $V_{GS}=-4.5$  V
- Fast Switching
- Pb-free lead plating; RoHS compliant


**Halogen-Free**

$V_{DS}$	-30	V
$R_{DS(on),TYP}$ @ $V_{GS}=-10$ V	22	$m\Omega$
$R_{DS(on),TYP}$ @ $V_{GS}=-4.5$ V	37	$m\Omega$
$I_D$	-30	A

**DFN2x2**


Part ID	Package Type	Marking	Tape and reel information
VS3522AA	DFN2x2	3522	3000PCS/Reel

**Drain Pin 1,2,5,6,7**

**Gate Pin 3**
**Source Pin 4,8**

## Maximum ratings, at $T_A = 25^\circ C$ , unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	-30	V
$V_{GS}$	Gate-Source voltage	$\pm 20$	V
$I_S$	Diode continuous forward current	$T_C = 25^\circ C$	A
$I_D$	Continuous drain current @ $V_{GS}=-10V$	$T_C = 25^\circ C$	A
		$T_C = 100^\circ C$	A
$I_{DM}$	Pulse drain current tested ①	$T_C = 25^\circ C$	A
$I_{DSM}$	Continuous drain current @ $V_{GS}=-10V$	$T_A = 25^\circ C$	A
		$T_A = 70^\circ C$	A
$P_D$	Maximum power dissipation	$T_C = 25^\circ C$	W
$P_{DSM}$	Maximum power dissipation ②	$T_A = 25^\circ C$	W
MSL		Level 3	
$T_{STG}, T_J$	Storage and Junction Temperature Range	-55 to 150	°C

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	°C/W



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Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ <math>T_j=25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	$\mu\text{A}$
	Zero Gate Voltage Drain Current( $T_j=125^\circ\text{C}$ )	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.3	-2	-2.4	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ③	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-4.5\text{A}$	--	22	29	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ③	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-4\text{A}$	--	37	48	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	750	850	950	pF
$C_{\text{oss}}$	Output Capacitance		80	140	200	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		40	95	150	pF
$R_g$	Gate Resistance	f=1MHz	--	11	--	$\Omega$
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-4.5\text{A}, V_{\text{GS}}=-10\text{V}$	--	18.2	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	4.9	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	5.6	--	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_{\text{D}}=-4.5\text{A}, R_{\text{G}}=0.75\Omega, V_{\text{GS}}=-10\text{V}$	--	10	--	nS
$t_r$	Turn-on Rise Time		--	32	--	nS
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		--	24	--	nS
$t_f$	Turn-Off Fall Time		--	28	--	nS
<b>Source- Drain Diode Characteristics@ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{\text{SD}}$	Forward on voltage	$I_{\text{SD}}=-4.5\text{A}, V_{\text{GS}}=0\text{V}$	--	-0.9	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{sd}}=-4.5\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=-100\text{A}/\mu\text{s}$	--	25	--	nS
$Q_{\text{rr}}$	Reverse Recovery Charge			16		nC

NOTE:

- ① Repetitive rating; pulse width limited by max junction temperature.
- ② The power dissipation  $P_{\text{DSM}}$  is based on  $R_{\text{GJA}}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ .
- ③ Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .



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## Typical Characteristics

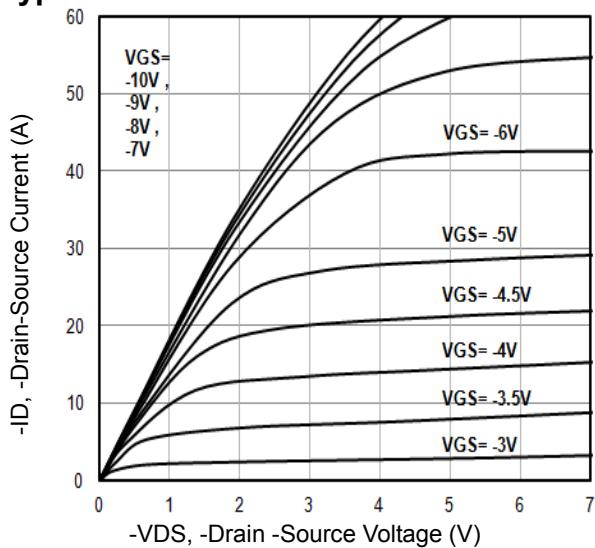


Fig1. Typical Output Characteristics

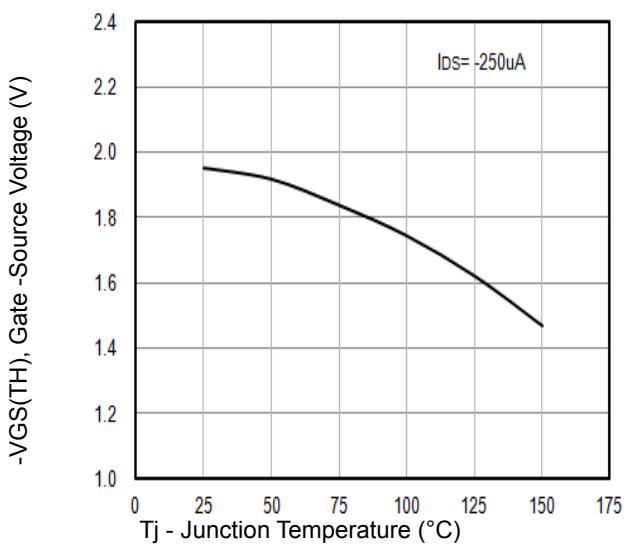


Fig2.  $-VGS(TH)$  Gate-Source Voltage Vs.  $T_j$

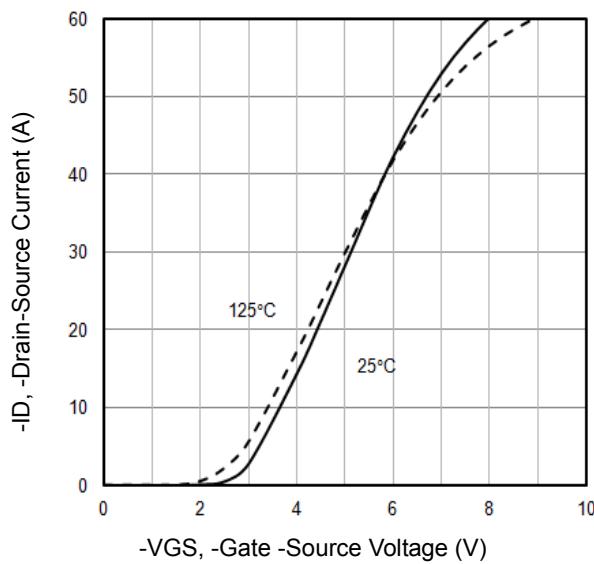


Fig3. Typical Transfer Characteristics

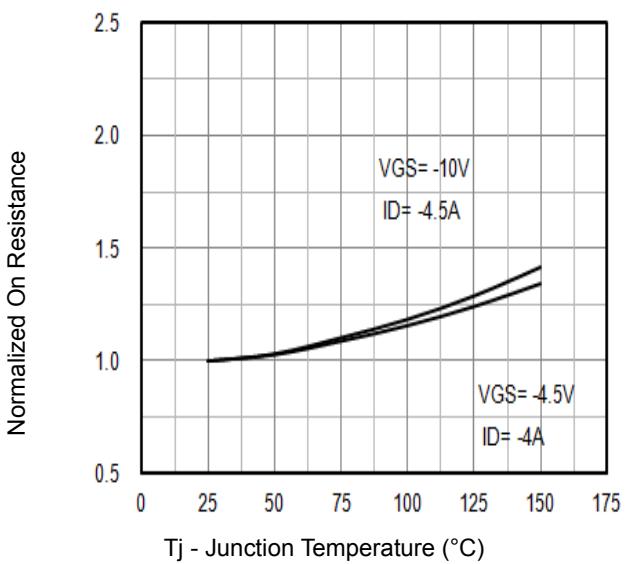


Fig4. Normalized On-Resistance Vs.  $T_j$

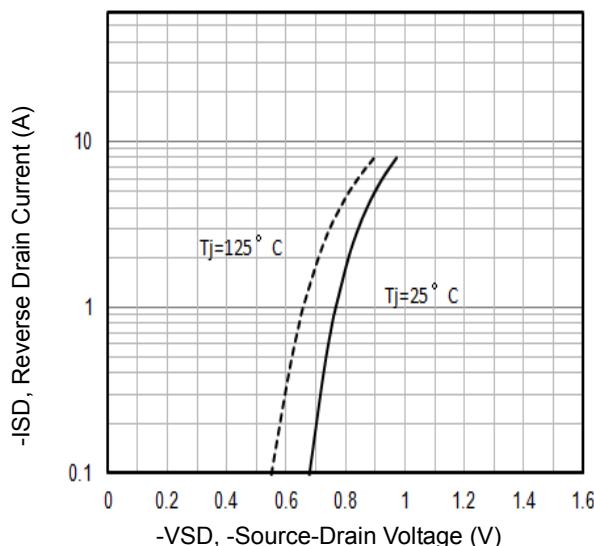


Fig5. Typical Source-Drain Diode Forward Voltage

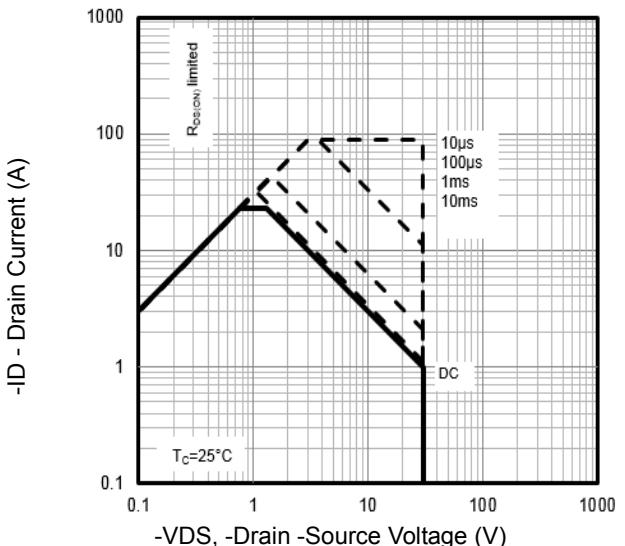


Fig6. Maximum Safe Operating Area



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## Typical Characteristics

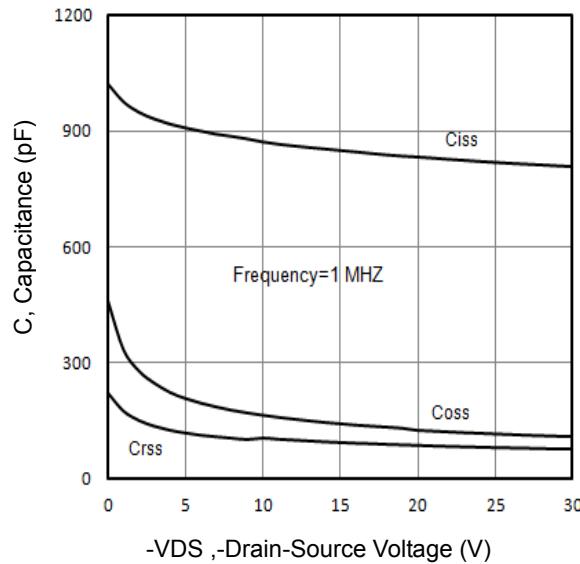


Fig7. Typical Capacitance Vs.Drain-Source Voltage

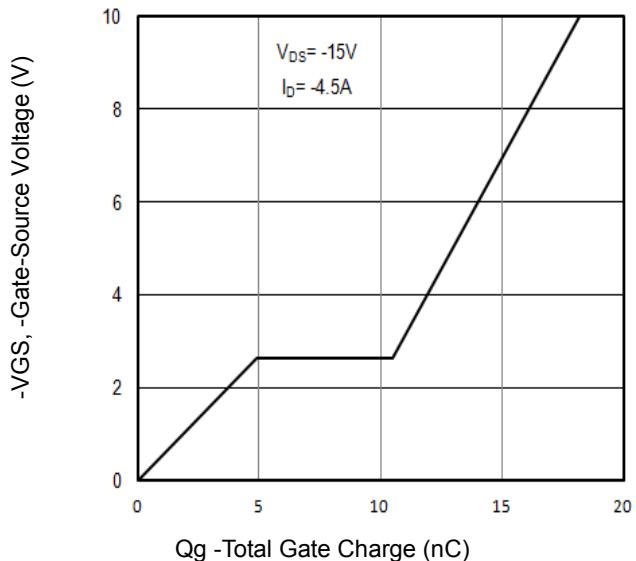


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

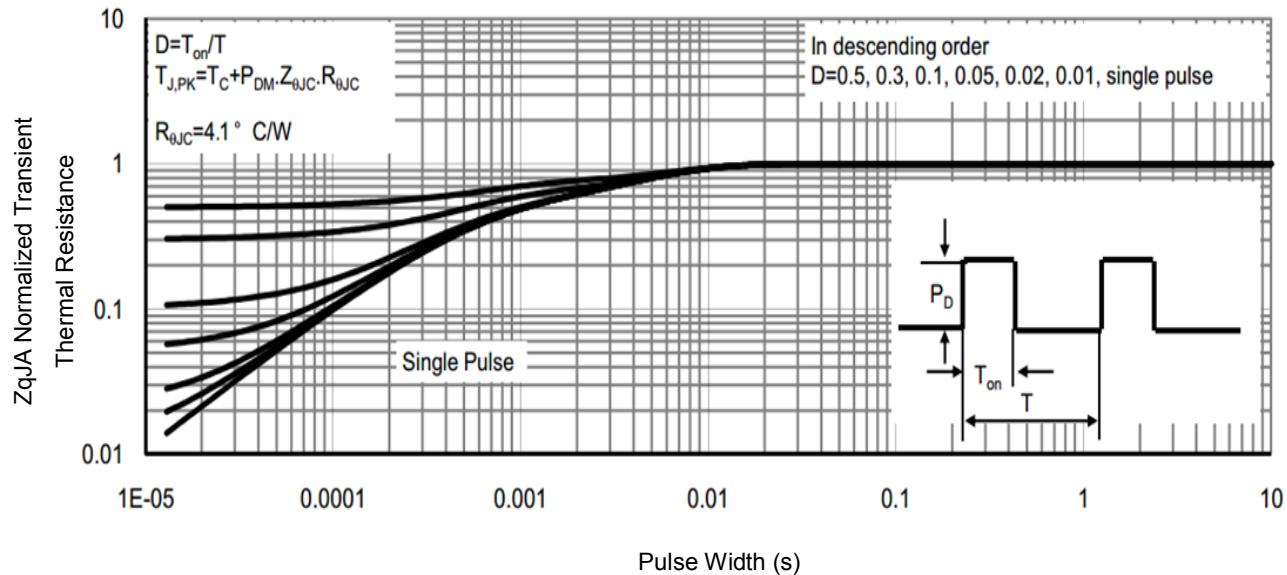


Fig9. Normalized Maximum Transient Thermal Impedance

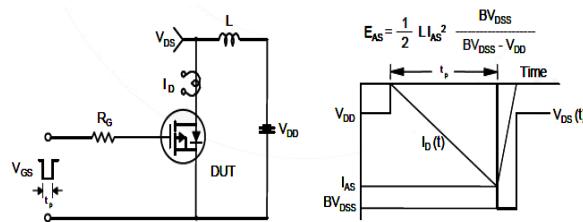


Fig10. Unclamped Inductive Test Circuit and waveforms

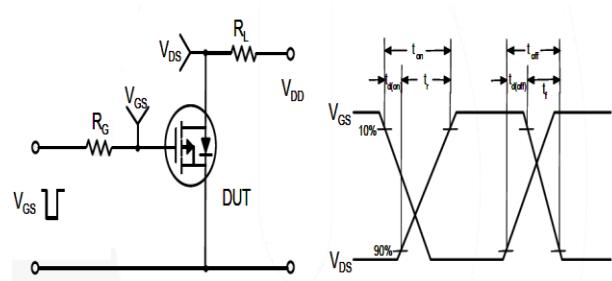


Fig11. Switching Time Test Circuit and waveforms



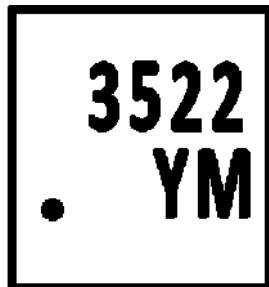
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**Marking Information**



1<sup>st</sup> line: Part Number (3522)

2<sup>nd</sup> line: Y: Year Code, e.g. E means 2017

M: Month Code

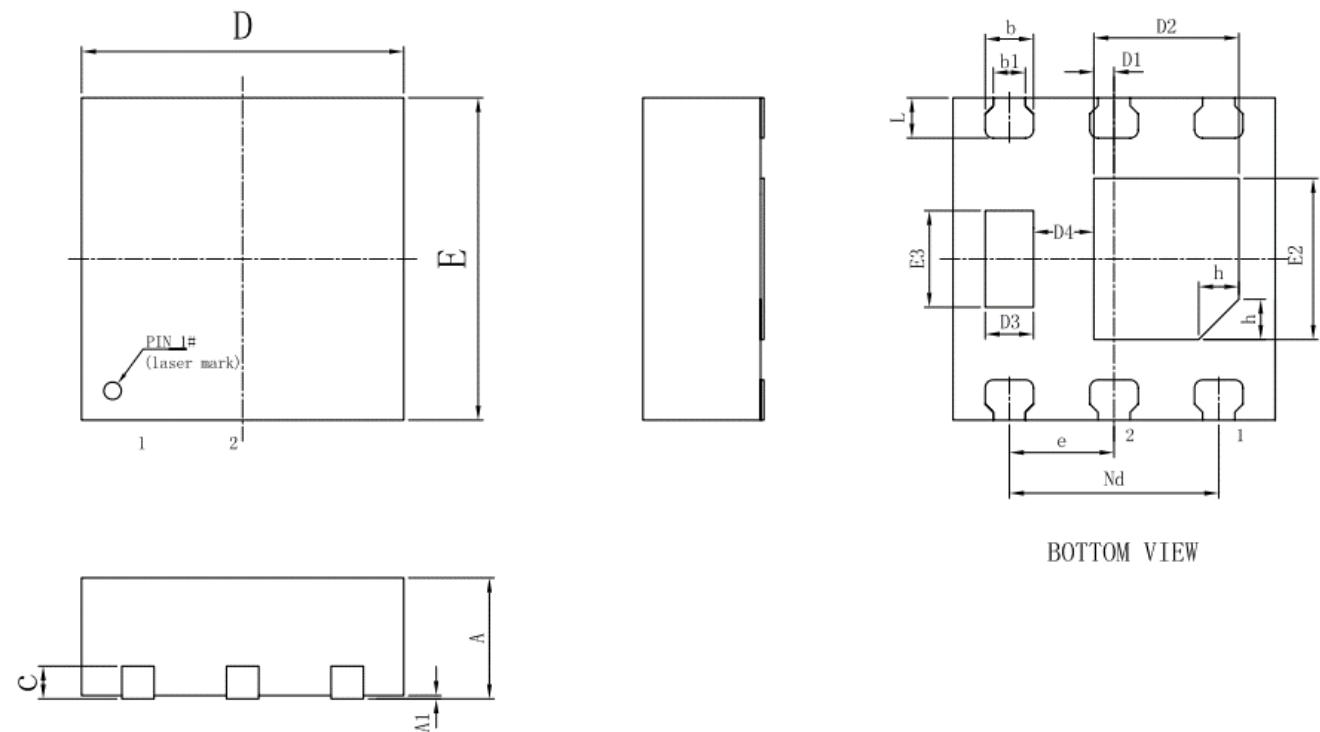


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### DFN2x2 Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	0.70	0.75	0.80
A1	--	0.02	0.05
b	0.25	0.30	0.35
b1	0.20 REF		
c	0.203 REF		
D	1.90	2.00	2.1
D1	0.08	0.125	0.18
D2	0.85	0.90	0.95
D3	0.25	0.3	0.35
D4	0.33	0.375	0.43
e	0.65 BSC		
Nd	1.30 BSC		
E	1.90	2.00	2.10
E2	0.95	1.00	1.05
E3	0.55	0.60	0.65
L	0.20	0.25	0.30
h	0.25 REF		

### Customer Service

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